Silicon P-Channel MOS FET

HITACHI

Application

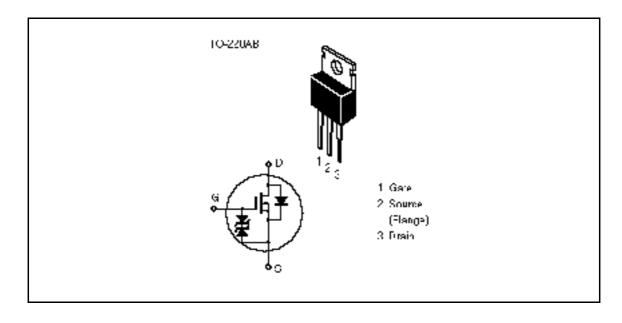
High frequency and low frequency power amplifier, high speed power switching

Complementary pair with 2SK213, 2SK214, 2SK215, 2SK216

Features

- Suitable for direct mounting
- High forward transfer admittance
- · Excellent frequency response
- Enhancement-mode

Outline





Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

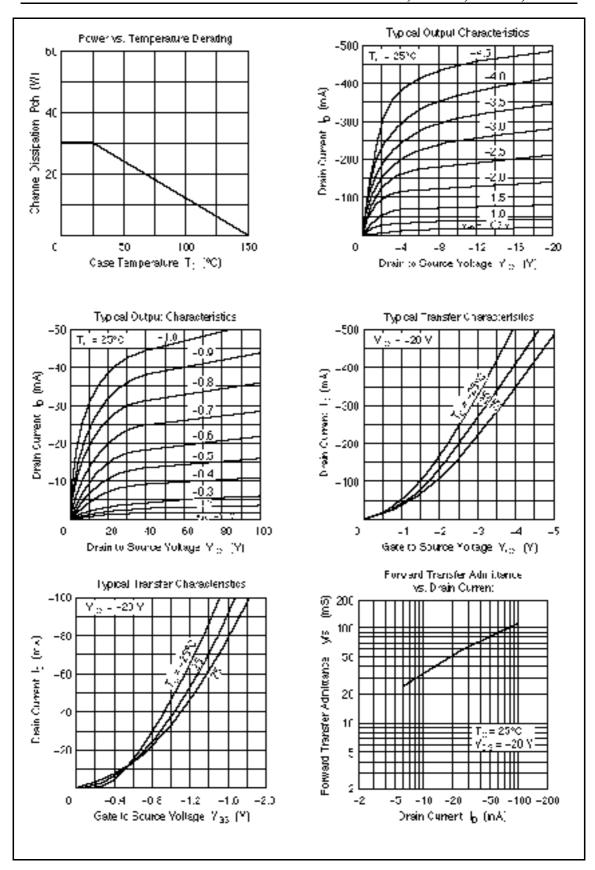
Item		Symbol	Ratings	Unit	
Drain to source voltage	2SJ76	V _{DSX}	-140	V	
	2SJ77		-160		
	2SJ78		-180		
	2SJ79		-200		
Gate to source voltage		V_{GSS}	±15	V	
Drain current		I _D	-500	mA	
Body to drain diode reverse drain current		I _{DR}	-500	mA	
Channel dissipation		Pch	1.75	W	
		Pch*1	30	W	
Channel temperature		Tch	150	°C	
Storage temperature		Tstg	-45 to +150	°C	

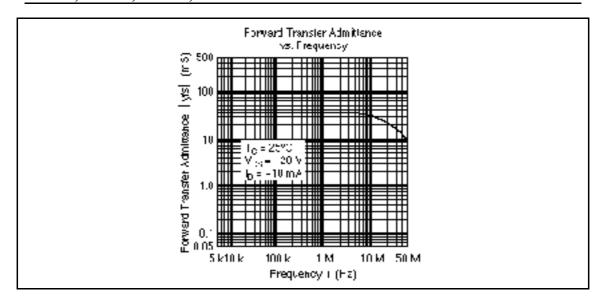
Note: 1. Value at $T_c = 25^{\circ}C$

Electrical Characteristics ($Ta = 25^{\circ}C$)

Item		Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source	2SJ76	$V_{(BR)DSX}$	-140	_	_	V	$V_{GS} = 2 \text{ V}, I_{D} = -1 \text{ mA}$
breakdown voltage	2SJ77	_	-160	_	_	V	_
	2SJ78	_	-180	_	_	V	_
	2SJ79	_	-200	_	_	V	_
Gate to source breakdown voltage		$V_{(BR)GSS}$	±15	_	_	V	$I_{G} = \pm 10 \ \mu A, \ V_{DS} = 0$
Gate to source volta	ge	$V_{\rm GS(on)}$	-0.2	_	-1.5	V	$I_D = -10 \text{ mA}, V_{DS} = -10 \text{ V}^{*1}$
Drain to source satu voltage	ration	$V_{\text{DS(sat)}}$	_	_	-2.0	V	$I_D = -10 \text{ mA}, V_{GD} = 0 *1$
Forward transfer add	mittance	y _{fs}	20	35	_	mS	$I_D = -10 \text{ mA}, V_{DS} = -20 \text{ V}^{*1}$
Input capacitance		Ciss	_	120	_	pF	$V_{DS} = -10 \text{ V}, I_{D} = -10 \text{ mA},$
Reverse transfer capacitance		Crss	_	4.8	_	pF	f = 1 MHz

Note: 1. Pulse test





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